Chip Scale Review®
ChipScaleReview.com
The Future of Semiconductor Packaging

2019 Editorial Calendar

July • August

(Editorial close date: 6/14)

Topics	Industry Events * indicates show distribution
Advances in inspection	• **ICEPT 2019** Shanghai, China (Aug 11-15)
Inkjet printing for packaging applications	• **SEMICON Taiwan *** Taipei, Taiwan (Sept 18-20)
Temporary bonding for high temperature processing of thin glass	• **European MEMS & Sensors Summit** Grenoble, France (Sept 19-21)
Reliability physics analysis	• **European Imaging & Sensors Summit** Grenoble, France (Sept 19-21)
Advanced IC and MEMS packaging technologies	
MEMS & Sensors	
Ultra-thin packaged ICs	
Glass carriers for temporary bonding	
Large-area fan-out processing	

Ad Space Close Jun 28 - Ad Materials Close Jul 8

September • October

(Editorial close date: (8/2))

Topics	Industry Events * indicates show distribution
Effective, Scalable EMI Protection	• **SMTA International *** Rosemont, IL (October 24-25)
Embedded RDL	• **IWLPC-International Wafer-Level Packaging Conference & Exhibition *** San Jose, CA (Oct 22-24)
High density flip-chip and advanced CSP	• **IMPACT** Taipei, Taiwan (October 24-26)
High-resolution 3D X-ray metrology	• **TestConX China 2019** Suzhou, China (Oct 23) Shenzhen, China (Oct 25)
Advanced substrates and embedded packaging	• **International Test Conference (ITC)** Phoenix, AZ (Oct 28- Nov 2)
High density advanced packaging (HDAP) design	• **SEMI International Technology Partners Conference (ITPC)** Maui, Hawaii (Nov 4-7)
Direct-placement process for LED’s	• **SEMICON Europa / Productronica** Munich, Germany (Nov 12-16)
Inkjet printing for packaging applications	

International Directory of Defect Inspection Systems

Ad Space Close Sep 6 - Ad Materials Close Sep 13

November • December

(Editorial close date: 10/4)

Topics	Industry Events * indicates show distribution
Collective bonding for heterogeneous integration	• **EPTC 2019 *** Singapore (Dec 3-6)
Cooling solutions for hi-density chips	• **SEMICON Japan** Tokyo, Japan (Dec 11-13)
Advanced eWLB for mmWave applications	• **SEMI European 3D Summit *** Dresden, Germany (TBD)
High temperature survivability & the processes it allows	• **SEMICON Korea 2020** Coex, Seoul, Korea (Feb 5-7, 2020)
TSV and RDL technologies, the road ahead	
Multi-die/ substrate heterogeneous packages	
3D ICs	

Ad Space Close Nov 3 - Materials Close Nov 10

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Notes: Editorial calendar topics and distribution are subject to change without notice and are contingent on logistics and magazine production.

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